

N-Channel 200 V (D-S) MOSFET

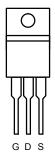
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)		
200	0.058at V _{GS} = 10 V	35		

FEATURES

- TrenchFET[®] Power MOSFETS
- 175 °C Junction Temperature
- New Low Thermal Resistance Package
- Compliant to RoHS Directive 2002/95/EC

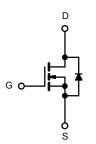






APPLICATIONS

Industrial



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	200	V			
Gate-Source Voltage	V _{GS}	± 20	v			
Continuous Drain Current (T _{.1} = 175 °C)	T _C = 25 °C	I-	35			
Continuous Diam Current (1) = 173 C)	T _C = 125 °C	l _D	23	A		
Pulsed Drain Current	I _{DM}	70	7 ^			
Avalanche Current	I _{AR}	35				
Repetitive Avalanche Energy ^a	L = 0.1 mH	E _{AR}	61	mJ		
Marian and Device Discipations	T _C = 25 °C	P _D	300 ^b	W		
Maximum Power Dissipation ^a	T _A = 25 °C ^c	- FD	3.75	VV		
Operating Junction and Storage Temperature Ra	inge	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	40	°C/W		
Junction-to-Case (Drain)	R _{thJC}	0.5	C/VV		

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).



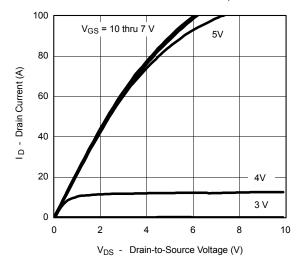
Parameter	Symbol	Test Conditions	Min .	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 \text{ V, } I_{D} = 250 \mu\text{A}$	V _{DS} = 0 V, I _D = 250 μA 200			- V	
Gate Threshold Voltage	V _{GS(th)}	$V_{\rm GS(th)}$ $V_{\rm DS} = V_{\rm GS}$, $I_{\rm D} = 250~\mu{\rm A}$			4		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 30 \text{ V}$			± 250	nA	
		V _{DS} = 200 V, V _{GS} = 0 V			1	μА	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 200 V, V _{GS} = 0 V, T _J = 125 °C			50		
		V _{DS} = 200 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	70			Α	
		V _{GS} = 10 V, I _D = 20 A		0.058			
5 . 6 . 6		V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.130		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.170			
		V _{GS} = 6 V, I _D = 15 A		0.070			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		70		S	
Dynamic ^b	'			•	· · · · · · · · · · · · · · · · · · ·		
Input Capacitance	C _{iss}			2690		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		200			
Reverse Transfer Capacitance	C _{rss}			110			
Total Gate Charge ^c	Qg			95	140	nC	
Gate-Source Charge ^c	Q_{gs}	V _{DS} = 100 V, V _{GS} = 10 V, I _D = 45 A		28			
Gate-Drain Charge ^c	Q_{gd}			34			
Gate Resistance	R _g	f = 1 MHz		1.6		Ω	
Turn-On Delay Time ^c	t _{d(on)}			22	35		
Rise Time ^c	t _r	V_{DD} = 100 V, R_{L} = 2.78 Ω		220	330	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 45 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		40	60		
Fall Time ^c	t _f			145	220		
Source-Drain Diode Ratings and Cha	aracteristics (T _C = 25 °C) ^b					
Continuous Current	I _S				45		
Pulsed Current	I _{SM}				70	Α	
Forward Voltage ^a	V _{SD}	I _F = 45 A, V _{GS} = 0 V		1	1.5	V	
Reverse Recovery Time	t _{rr}			150	225	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 45 A, di/dt = 100 A/μs		12	18	Α	
Reverse Recovery Charge	Q _{rr}			0.9	2	μC	

- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

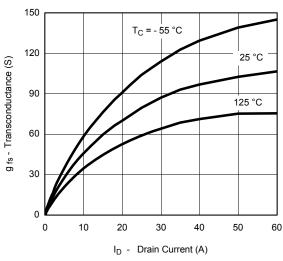
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



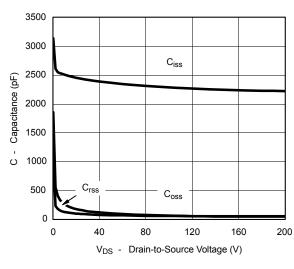
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



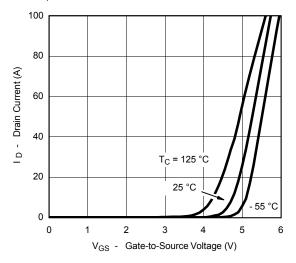
Output Characteristics



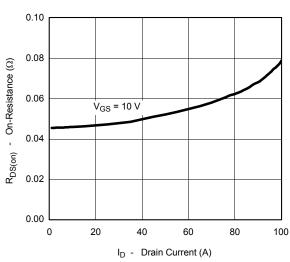
Transconductance



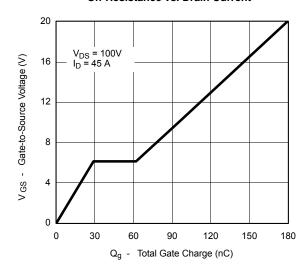
Capacitance



Transfer Characteristics



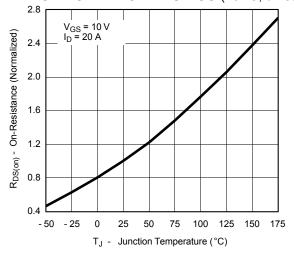
On-Resistance vs. Drain Current



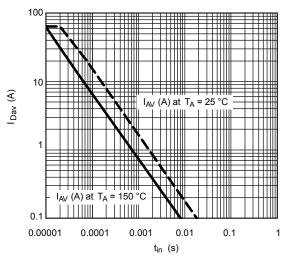
Gate Charge



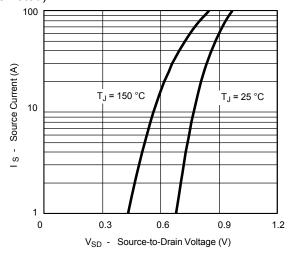
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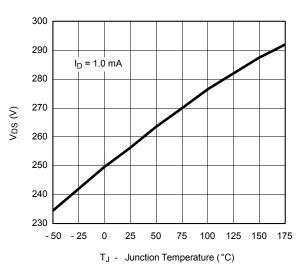
On-Resistance vs. Junction Temperature



Avalanche Current vs. Time



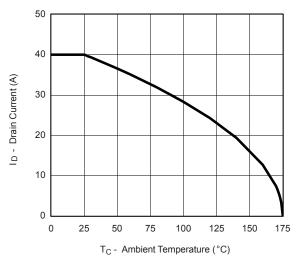
Source-Drain Diode Forward Voltage

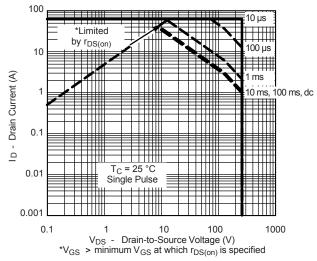


Drain Source Breakdown vs. Junction Temperature



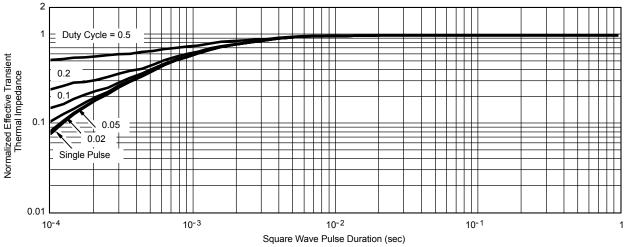
THERMAL RATINGS





Maximum Avalanche and Drain Current vs. Case Temperature

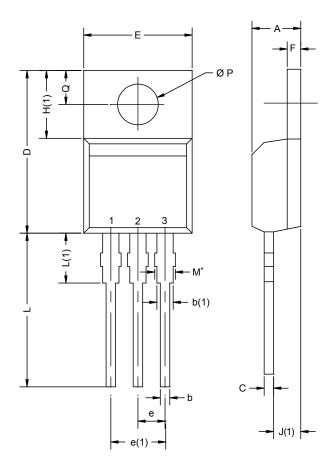
Safe Operating Area, Case Temperature



Normalized Thermal Transient Impedance, Junction-to-Case



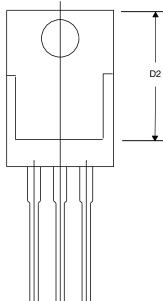
TO-220AB



	MILLIN	IETERS	INC	INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
D2	12.19	12.70	0.480	0.500	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØР	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471					

Note

 * M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM





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